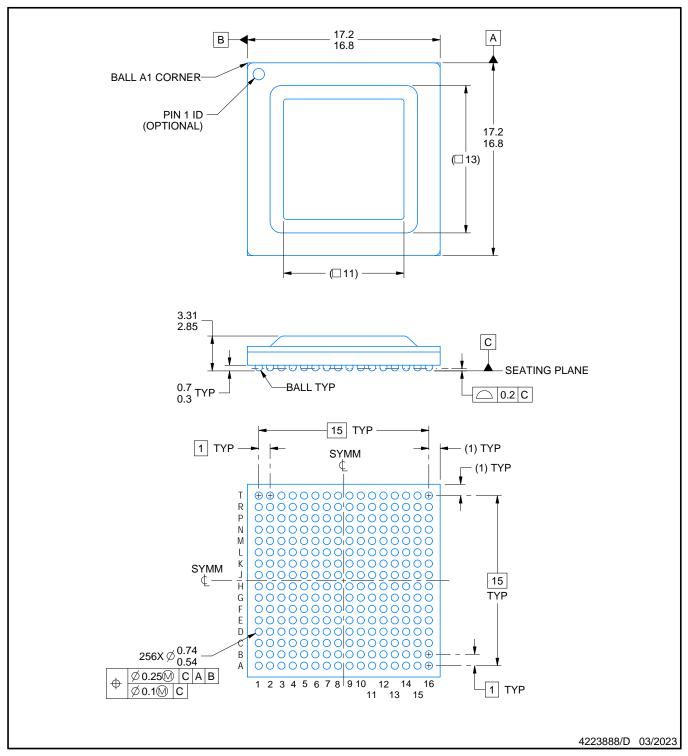


BALL GRID ARRAY

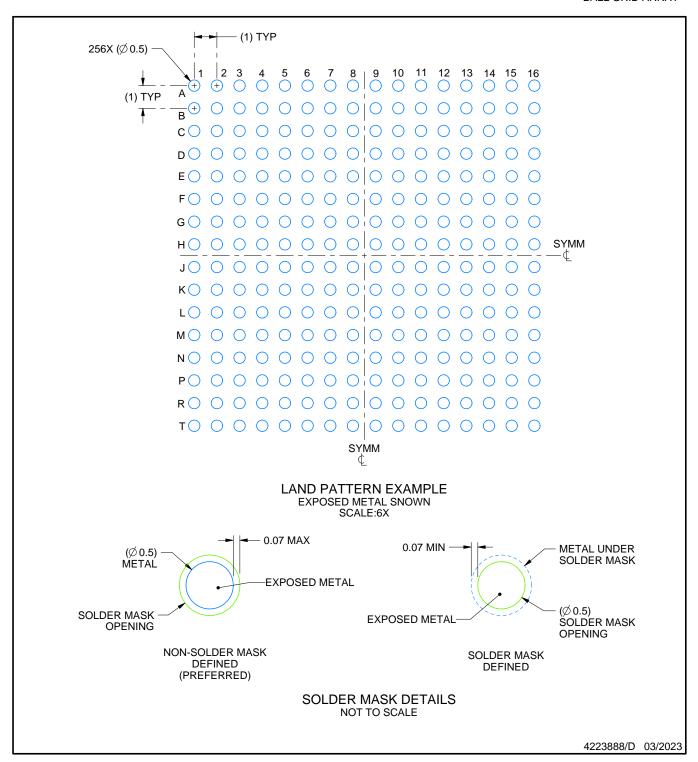


NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. Pb-Free die bump and solder ball.
- 4. The lids are electrically floating (e.g. not tied to GND).



BALL GRID ARRAY

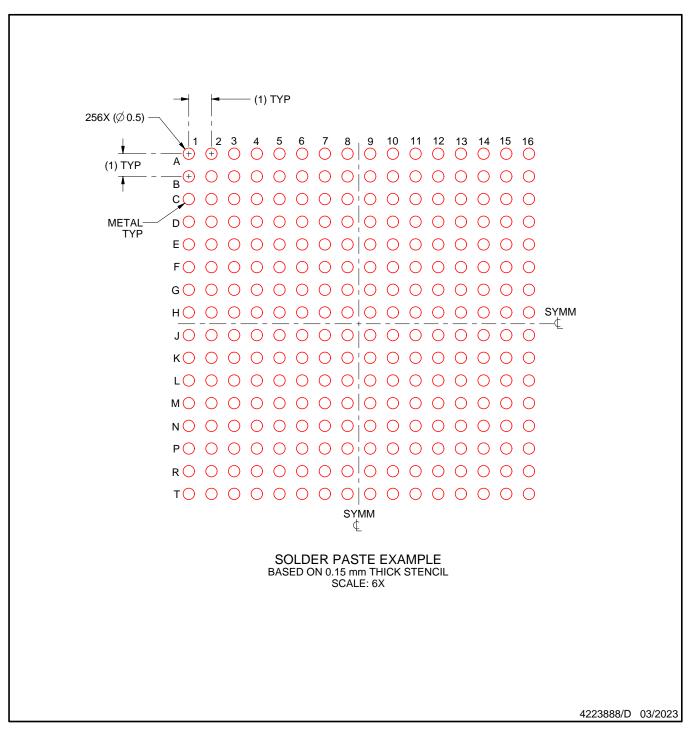


NOTES: (continued)

Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.For more information, see Texas Instruments literature number SPRU811 (www.ti.com/lit/spru811).



BALL GRID ARRAY



NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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